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## **TIS75**

### **N-Channel General Purpose Amplifier**

- This device is designed for low level analog switching, sample and hold circuits and chopper stabilized amplifiers.
- Sourced from process 54.



1. Gate 2. Source 3. Drain

# **Absolute Maximum Ratings \*** $T_a$ =25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{DG}$	Drain-Gate Voltage	30	V
$V_{GS}$	Gate-Source Voltage	-30	V
I <sub>GF</sub>	Forward Gate Current	10	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### **Electrical Characteristics** T<sub>a</sub>=25°C unless otherwise noted

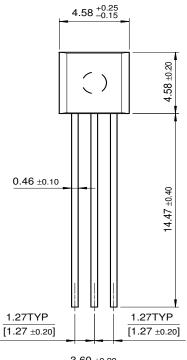
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
Off Charac	teristics	•				•
V <sub>(BR)GSS</sub>	Gate-Source Breakdown Voltage	$I_{G} = 1.0 \mu A, V_{DS} = 0$	-30			V
GSS	Gate Reverse Current	$V_{GS} = 15V, V_{DS} = 0$ $V_{GS} = 15V, V_{DS} = 0, T_a = 100^{\circ}C$			-2.0 -5.0	nA ^
<sub>D</sub> (off)	Drain Cutoff Leakage Current	$V_{GS} = 15V$ , $V_{DS} = 0$ , $I_a = 100 \text{ C}$ $V_{DS} = 15V$ , $V_{GS} = -10V$ , $V_{DS} = 15V$ , $V_{GS} = -10V$ , $V_{GS} = 100^{\circ}\text{C}$			-2.0 -5.0	μA nA μA
V <sub>GS</sub> (off)	Gate-Source Cutoff Voltage	$V_{DS} = 20V, I_D = 4.0nA$	-0.8		-4.0	V
On Charac	teristics *	•				•
I <sub>DSS</sub>	Zero-Gate Voltage Drain Current *	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0	8		80	mA
<sub>DS</sub> (on)	Drain-Source On Resistance	$V_{DS} \le 0.1 V, V_{GS} = 0$			60	Ω
Small Sign	al Characteristics	•				•
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 0$ , $V_{GS} = -10V$ , $f = 1.0MHz$			18	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	$V_{DS} = 0$ , $V_{GS} = -10V$ , $f = 1.0MHz$			8.0	pF
Switching	Characteristics	•				•
t <sub>r</sub>	Rise Time	$V_{GS}(off) = -4.0V, V_{GS}(on) = 0,$			10	ns
t <sub>on</sub>	Turn-On Time	$I_D = 5.0 \text{mA}, V_{DS} = 10 \text{V}$			10	ns
t <sub>off</sub>	Turn-Off Time				100	ns

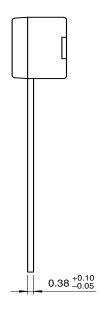
<sup>\*</sup> Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 3.0%

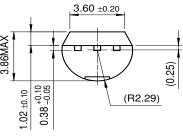
Thermal Characteristics T <sub>a</sub> =25°C unless otherwise noted				
Symbol	Parameter	Max.	Units	
P <sub>D</sub>	Total Device Dissipation Derate above 25°C	350 2.8	mW mW/ <sup>o</sup> C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W	
$\frac{R_{\theta JC}}{R_{\theta JA}}$	Thermal Resistance, Junction to Ambient	357	°C/W	

# **Package Dimensions**

TO-92







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#### **Definition of Terms**

Datasheet Identification	Product Status	Definition
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